L Number		Search Text	DB	Time stamp
-	54	system and substrate and (print\$6 adj circuit adj board 'PCB'	USPAT:	2004/11/05 11:15
		aluminum near2 frame grid near2 array) and ((polymer	US-PGPUB	255 11 1705 11.15
		thermoplastic thermoset photo\$2resist DNQ\$4	1 3 3 3 5 5	
		diazonaphthoquinone novolac epoxy polyamide) and		ľ
		(magnetic ferro\$2magnetic titanate barium adi strontium adi		
		titanate strontium adj tantalum adj oxide perovskite iron		
		cobalt nickel)) near7 (interconnect\$4 coupl\$4 packag\$4)		
	1	and (particle grain) near2 (size diameter 'nm' micron) and		
		(acicular flake (length width aspect diameter) near2 ratio)		1
-	20	system and substrate and (print\$6 adj circuit adj board 'PCB'	USPAT:	2004/11/05 11:15
		aluminum near2 frame grid near2 array) and ((polymer	US-PGPUB	2004/11/05 11.15
		thermoplastic thermoset photo\$2resist DNO\$4	0010100	
		diazonaphthoquinone novolac epoxy polyamide) and (		
	1	titanate barium adj strontium adj titanate strontium adj		
	ļ	tantalum adj oxide perovskite )) near5 particle and		
		(interconnect\$4 coupl\$4 packag\$4)		
-	91	system and substrate near5 (interconnect\$4 coupl\$4	USPAT;	2004/44/05 44:45
		packag\$4) and (print\$6 adj circuit adj board 'PCB' aluminum	US-PGPUB	2004/11/05 11:15
		near2 frame grid near2 array) and (polymer thermoplastic	03-FGF0B	
	1 1	thermoset photo\$2resist DNQ\$4 diazonaphthoquinone		
		novolac epoxy polyamide) and (magnetic ferro\$2magnetic		1
		titanate barium adj strontium adj titanate strontium adj		
	1 1	tantalum adj oxide perovskite iron cobalt nickel ) near5		
		(particle flake) and (particle grain) near2 (size diameter 'nm'		
		micron ultra\$2fine) and (acicular flake (length width aspect		
		diameter) near2 ratio)		
-	4	system and substrate with (interconnect\$4 coupl\$4	USPAT;	2004/11/05 11:15
	1 1	packag\$4) with component and (print\$6 adj circuit adj board	US-PGPUB	2004/11/05 11:15
		PCB aluminum near2 frame grid near2 array) and (nolymer	00-1 01-08	
	[	thermoplastic thermoset photo\$2resist DNO\$4		
	1	diazonaphthoquinone novolac epoxy polyamide) and		
	1	(titanate barium adj strontium adj titanate strontium adj		
	]	tantalum adj oxide perovskite ) near5 (particle flake)		
-	5	screen adj pad and (printed adj circuit adj board 'PCB' grid	USPAT:	2004/11/05 11:16
		near5 array aluminum near2 frame) and (interconnect	US-PGPUB	2004/11/05 11:16
	·	packaging magnetically near5 align\$3)	00 1 01 05	
	26	((polymer thermoplastic thermoset photo\$2resist DNO\$4	USPAT;	2004/11/05 11:16
		diazonaphthoquinone novolac epoxy polyamide) and	US-PGPUB	2004/11/05 11.16
İ	İ	(magnetic ferro\$2magnetic titanate iron magnetite harium	001000	
		adj strontium adj titanate strontium adj tantalum adj oxide		
		perovskite iron cobalt nickel 'fe' 'co' 'ni' ) and (particle powder		
		fiber grain) near5 align\$4 near5 magnetic) and conductive		
		near5 interconnect		
	20	( ((polymer thermoplastic thermoset polyamide epoxy	EPO; JPO;	2004/11/05 11:16
ŀ	[ ]	photo\$2resist DNQ\$4 diazonaphthoguinone novolac) and	DERWENT;	2004/11/05 11:16
		(magnetic ferro\$2magnetic titanate iron magnetite	IBM TDB	
	11	perovskite)) and (particle powder fiber grain) near5 align@4)	.51.00	
i		and (conductive interconnect\$4 packag\$4)		
ļ	16   (	("5232661" "5536908" "5526978" "5545367" "5618189"	USPAT;	2004/11/05 10:10
	'	"5846854" "09023049" "01052303").did.	US-PGPUB;	2004/11/05 12:46
	[	- /	EPO; JPO;	
			DERWENT	